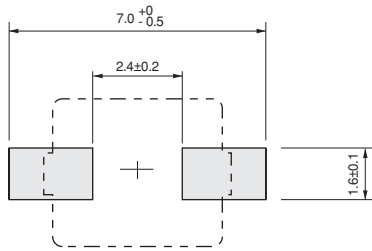


Mounting

Land Pattern

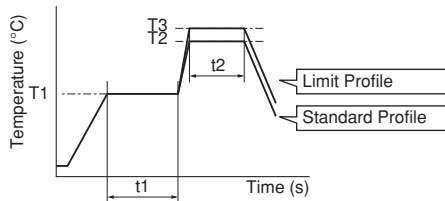


(in mm)

Soldering Profile

Flow Soldering Profile

Soldering profile for Lead-free solder (96.5Sn/3Ag/0.5Cu), Eutectic solder (63Sn/37Pb)



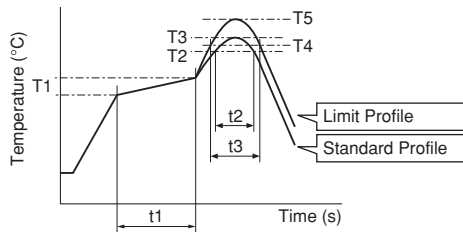
• Immerse the body in solder bath, available for cover film type.

Standard Profile				
Pre-heating		Heating		Cycle of Reflow
Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	
150°C	60 to 120sec.	250°C	5sec. max.	1 time

Limit Profile				
Pre-heating		Heating		Cycle of Reflow
Temp. (T1)	Time (t1)	Temp. (T3)	Time (t2)	
150°C	60 to 120sec.	265±3°C	5sec. max.	2 times

Reflow Soldering Profile

① Soldering profile for Lead-free solder (96.5Sn/3Ag/0.5Cu)



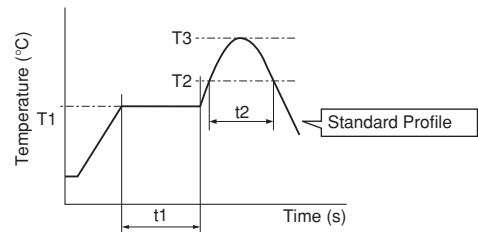
Standard Profile					
Pre-heating		Heating		Peak Temperature (T3)	Cycle of Reflow
Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)		
150 to 180°C	60 to 120sec.	220°C	30 to 60sec.	245±3°C	2 times

Limit Profile					
Pre-heating		Heating		Peak Temperature (T5)	Cycle of Reflow
Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)		
150 to 180°C	60 to 120sec.	230°C	30 to 50sec.	260 +5/-0°C	2 times

• Available for terminal shape A, B, and E.

② Soldering profile for Eutectic solder (63Sn/37Pb)

(Limit profile: refer to ①)



Standard Profile					
Pre-heating		Heating		Peak Temperature (T3)	Cycle of Reflow
Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)		
150°C	60 to 120sec.	183°C	30sec.	230 +5/-0°C	1 time

Soldering Iron

Standard Profile			
Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron
350±10°C	3sec. max.	30W max.	1 time